2SB0779 (2SB779)

Silicon PNP epitaxial planar type

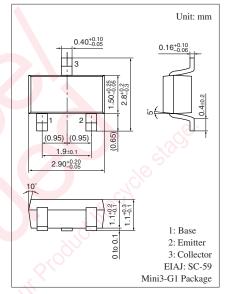
For low-frequency output amplification

Features

- \bullet Low collector-emitter saturation voltage $V_{\mbox{CE(sat)}}$
- Satisfactory linearity of forward current transfer ratio h_{FE} at the low collector voltage
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

Absolute Maximum Ratings $T_a = 25^{\circ}C$

	a		
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	-25	v
Collector-emitter voltage (Base open)	V _{CEO}	-20	V
Emitter-base voltage (Collector open)	V _{EBO}	-7	V
Collector current	I _C	-500	mA
Peak collector current	I _{CP}	-1	А
Collector power dissipation	P _C	200	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



Marking Symbol: 1A

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu A, I_{\rm E} = 0$	-25	25		V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -1 \text{ mA}, I_{\rm B} = 0$	-20			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = -10 \ \mu A, I_{\rm C} = 0$	-7			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -25 \text{ V}, I_E = 0$			-100	nA
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -20 \text{ V}, I_B = 0$			-1	μΑ
Forward current transfer ratio *1	h _{FE1} *2	$V_{CE} = -2 \text{ V}, \text{ I}_{C} = -500 \text{ mA}$	90		220	_
	h _{FE2}	$V_{CE} = -2 V, I_C = -1 A$	25			_
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_{\rm C} = -500 \text{ mA}, I_{\rm B} = -50 \text{ mA}$		- 0.2	- 0.4	V
Base-emitter saturation voltage *1	V _{BE(sat)}	$I_{\rm C} = -500 \text{ mA}, I_{\rm B} = -50 \text{ mA}$			-1.2	V
Transition frequency	f _T	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance (Common-emitter reverse transfer)	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		15		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *1: Pulse measurement

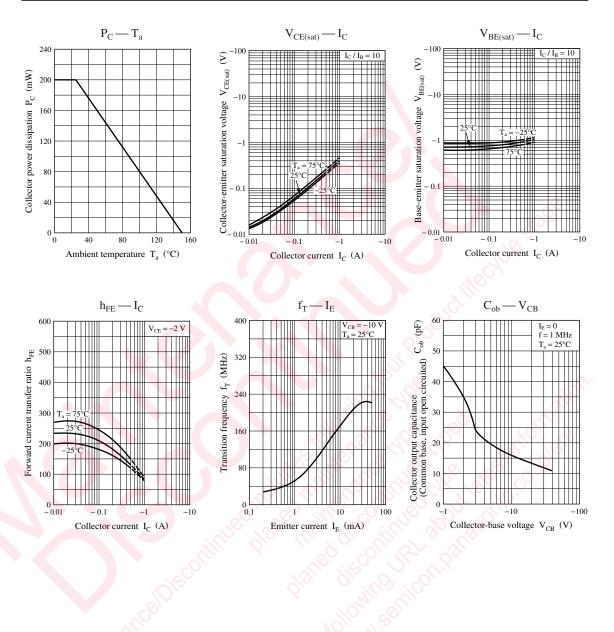
*2: F	ank c	lassification	
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Rank	Q	R
$h_{\rm FE1}$	90 to 155	130 to 220

Note) The part number in the parenthesis shows conventional part number.

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